CMHD3595

SURFACE MOUNT LOW LEAKAGE SILICON DIODE



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMHD3595 is a silicon diode, manufactured by the epitaxial planar process, epoxy molded in a surface mount package, designed for high conductance applications requiring low leakage.

MARKING CODE: C95



MAXIMUM RATINGS: (TA=25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	150	V
Peak Working Reverse Voltage	V_{RWM}	125	V
Average Forward Current	IO	150	mA
Continuous Forward Current	I _F	225	mA
Recurrent Peak Forward Current	i _f	600	mA
Peak Forward Surge Current, tp=1.0s	I _{FSM}	500	mA
Peak Forward Surge Current, tp=1.0μs	I _{FSM}	4.0	Α
Power Dissipation	P_{D}	400	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	ΘΙΔ	312.5	°C/W

ELECTRICAL CHARACTERISTICS: $(T_A=25^{\circ}\text{C unless otherwise noted)}$

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{R}	V _R =125V		1.0	nA
I_{R}	V _R =125V, T _A =125°C		2.0	μΑ
I_{R}	V _R =125V, T _A =150°C		5.0	μΑ
I_{R}	V _R =30V, T _A =125°C		300	nA
BV_R	I _R =100μA	150		V
V_{F}	I _F =1.0mA	0.54	0.69	V
V_{F}	I _F =5.0mA	0.62	0.77	V
VF	I _F =10mA	0.65	0.80	V
V_{F}	I _F =50mA	0.75	0.88	V
V_{F}	I _F =100mA	0.79	0.92	V
V_{F}	I _F =200mA	0.83	1.00	V
CJ	$V_R=0$, f=1.0MHz		8.0	pF
t _{rr}	V_R =3.5 V , I_F =10 m A, R_L =1.0 k Ω		3.0	μs

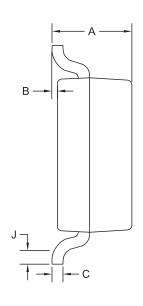
R6 (17-June 2019)

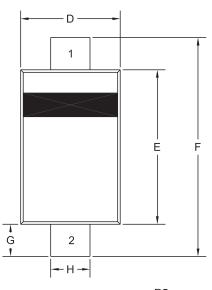
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SOD-123 CASE - MECHANICAL OUTLINE





R5

LEAD CODE1) Cathode

- 2) Anode

MARKING CODE: C95

DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.037	0.053	0.95	1.35			
В	0.000	0.005	0.00	0.12			
С	-	0.008	-	0.20			
D	0.055	0.071	1.40	1.80			
Е	0.098	0.110	2.50	2.80			
F	0.142	0.154	3.60	3.90			
G	0.016	-	0.40	-			
Н	0.020	0.028	0.50	0.70			
J	0.010	-	0.25	-			

SOD-123 (REV:R5)

R6 (17-June 2019)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA

Main Tel: (631) 435-1110 Main Fax: (631) 435-1824

Support Team Fax: (631) 435-3388

www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors:

www.centralsemi.com/wwdistributors

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